# OMRON

# EE-SX4330 Photomicrosensor (Transmissive)

Ultra-Compact Slot / SMD Type / Photo IC Output (Slot width: 3 mm)

• 3-mm slot width x SMD x Photo IC type Contributes to making the device compact and allowing free design for a variety of applications



Be sure to read Safety Precautions on page 5.

# Model Number Legend

EE-SX				0
(1)	(2)	(3)	(4)	

(1) Sensing method X: Transmissive (2) Operating mode 4: ON during light input (3) Connecting method 3: SMT (4) Sensing distance 3: 3 mm

# **Ordering Information**

### Photomicrosensor

Appearance	Sensing method	Connecting method	Sensing distance	Aperture size (H × W) (mm)	Output type	Model	Minimum number of deliverable units (Unit: pieces)	Package type
5	Transmissive	SMT	2 mm ( ) ( ) ( )	Emitter 1.4 × 1.4 Photo IC		EE-SX4330	1,000	Tape reel
6	(slot type)	SIMT	3 mm (slot width)	Detector 1 × 0.3		EE-SX4330-1	100	Tape cut

# **Ratings, Characteristics and Exterior Specifications**

#### Absolute Maximum Ratings (Ta = 25°C)

		•					
ltem		Symbol	Rated value	Unit			
Emitter							
	Forward current	lf	25 *1	mA			
	Reverse voltage	VR	5	V			
Detector							
Power supply voltage		Vcc	9	V			
Output voltage		Vout	17	V			
	Output current	Іоит	8	mA			
	Permissible output dissipation	Роит	80 *1	mW			
Oper	ating temperature	Topr	-30 to +85 *1	°C			
Storage temperature		Tstg	-40 to +90 *1	°C			
Reflow soldering temperature		Tsol	255 *²	°C			

**\*1.** Refer to the temperature rating chart if the ambient temperature exceeds 25°C.

\*2. Complete soldering within 10 seconds for reflow soldering.

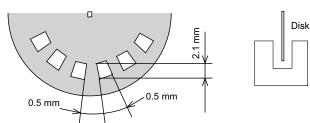
### **Exterior Specifications**

Connecting method	Weight (g)	Material	
Connecting method	weight (g)	Case	
SMT	0.2	PPS	

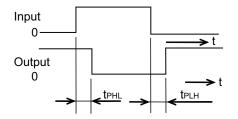
### Electrical and Optical Characteristics (Ta = 25°C)

Item	Symbol		Value		Unit	Condition
item	Gynibol	MIN.	TYP.	MAX.	onit	condition
Emitter						
Forward voltage	VF		1.4	1.65	V	IF = 20 mA
Reverse current	lR		0.01	10	μA	V <sub>R</sub> = 5 V
Peak emission wavelength	λp		855		nm	IF = 20 mA
Detector						•
Power supply voltage	Vcc	2.2		7	V	
Low-level output voltage	Vol		0.12	0.4	V	Vcc = 2.2 to 7 V, I⊧ = 7 mA, Io∟ = 8 mA
High-level output voltage	Іон			10	μA	Vcc = 2.2 to 7 V, IF = 0 mA, VoH = 17 V
Current consumption	lcc		2.8	4	mA	Vcc = 7 V
Peak spectral sensitivity wavelength	λp		870		nm	Vcc = 2.2 to 7 V
ED current when output is ON	IFT			3.5	mA	Vcc = 2.2 to 7 V
lysteresis	ΔH		21		%	Vcc = 2.2 to 7 V *1
Response frequency	f	3			kHz	Vcc = 2.2 to 7 V, IF = 5 mA, IoL = 8 mA *2
Poononoo dalay tima	<b>t</b> PLH		2		μs	$V_{CC} = 2.2 \text{ to } 7 \text{ V}, I_F = 5 \text{ mA},$ IoL = 8 mA *3
Response delay time	<b>t</b> PHL		37		μs	V <sub>CC</sub> = 2.2 to 7 V, I <sub>F</sub> = 5 mA, I <sub>OL</sub> = 8 mA * <sup>3</sup>

\*1. Hysteresis denotes the difference in forward LED current value, expressed in percentage, calculated from the respective forward LED currents when the photo IC in turned from ON to OFF and when the photo IC in turned from OFF to ON.
\*2. The value of the response frequency is measured by rotating the disk as shown below.



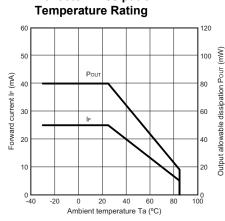
\*3. The following illustrations show the definition of response delay time.

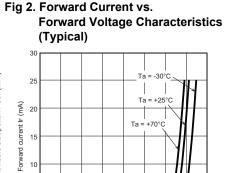


# **Engineering Data (Reference value)**

#### Fig 1. Forward Current vs. **Collector Dissipation**

Fig 4.LED Current vs.





15

10

0

0.2

0.4 0.6 Ta = +70°



**Output Current (Typical)** 

0.8

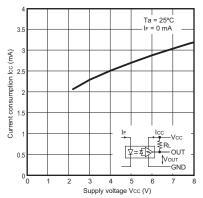
Forward voltage VF (V)

1.2 1.4 1.6

**Characteristics (Typical)** Vcc=5V RL=4.7kΩ 0.75 LED current IFT (mA) 0.5 FT ON 0.25 Vcc L OFF |**\$**≠€₿ Vout -GND 0 0 20 40 60 Ambient temperature Ta (°C) 80 40 -20 100

**Ambient Temperature** 

Fig 7. Current Consumption vs. Supply Voltage (Typical)



## Ta = 25°C Vcc = 5 V IoL = 8 mA Low level output voltage Vol. (V) 100 100 100 -Vcc GND 0.001 10 Output current Ic (mA)

Fig 8. Response Delay Time vs. Forward Current (Typical)

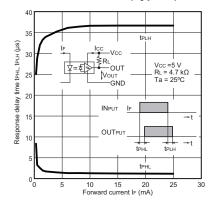


Fig 3. LED Current vs. Supply Voltage (Typical)

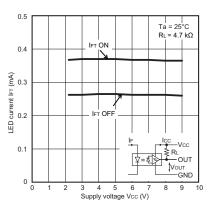


Fig 6. Low-level Output Voltage vs. **Ambient Temperature Characteristics (Typical)** 

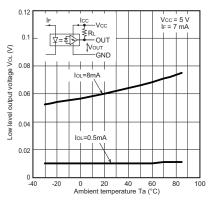
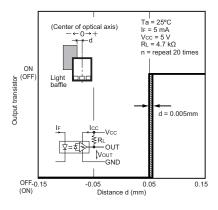


Fig 9. Repeat Sensing Position **Characteristics (Typical)** 



### **EE-SX4330**

# Dimensions and Internal Circuit

Ejector pin, gate mark, or flat surface 2.0 mm dia. or 0.5 mm recess (MAX)

(6)

(5)

(4)

(Unit: mm)

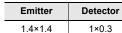
CAD Data

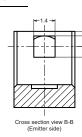
#### Photomicrosensor

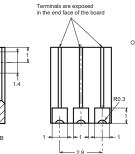
#### EE-SX4330

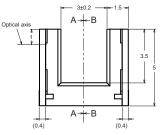


#### Aperture size (H x W)





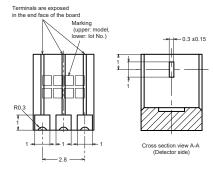




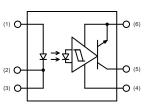
(6xC0.2)

(1) (2)

(3)

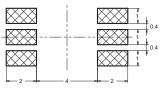






Terminal No.	Name
(1)	Anode
(2)(3)	Cathode
(4)	Power supply voltage
(5)	Output
(6)	ground

Recommended Soldering Pattern



Unless otherwise specified, the tolerances are ±0.2 mm.

# **Safety Precautions**

To ensure safe operation, be sure to read and follow the Instruction Manual provided with the Sensor.

#### A CAUTION

This product is not designed or rated for ensuring safety of persons either directly or indirectly. Do not use it for such purposes.



#### Precautions for Safe Use

Do not use the product with a voltage or current that exceeds the rated range.

Applying a voltage or current that is higher than the rated range may result in explosion or fire.

# Do not miswire such as the polarity of the power supply voltage.

Otherwise the product may be damaged or it may burn. **Do not short-circuit the load.** 

Otherwise explosion or burning may occur.

This product does not resist water. Do not use the product in places where water or oil may be sprayed onto the product.

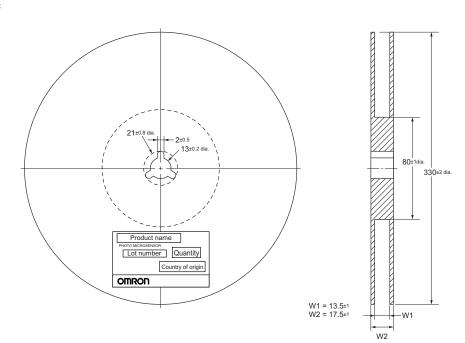
### **Tape and Reel**

Reel (Unit: mm) \*

Precautions for Correct Use

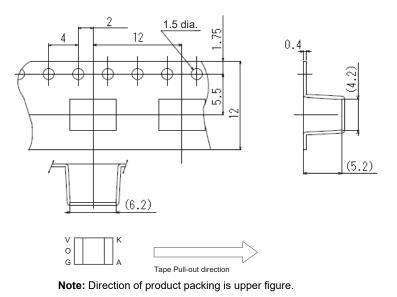
Do not use the product in atmospheres or environments that exceed product ratings. This product is for surface mounting. Refer to Soldering Information, Storage and Baking for details.

Dispose of this product as industrial waste.



## EE-SX4330

### Tape (Unit: mm)



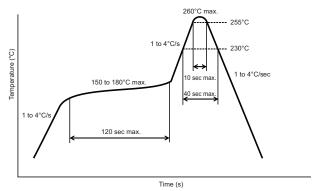
### Tape quantity

1,000 pcs./reel 100 pcs./pack **\* \*** EE-SX4330-1 (100 pcs./pack) has no reel, only tape is attached.

# **Soldering Information**

#### **Reflow soldering: Temperature profile**

- The reflow soldering can be implemented in two times complying with the following diagram.
- All the temperatures in the product must be within the diagram.
- 2. The recommended thickness of the metal mask for screen printing is between 0.2 and 0.25 mm.



### Storage

#### Storage conditions

To protect the product from the effects of humidity until the package is opened, dry-box storage is recommended. If this is not possible, store the product under the following conditions:

Temperature: 10 to 30 °C

Humidity: 60% RH max.

## Baking

In case that it could not carry out the above treatment, it is able to mount by the following baking treatment. However baking treatment shall be limited only 1 time.

Recommended conditions: 60°C for 24 to 48 hours (reeled one) 100°C for 8 to 24 hours (loose one)

#### Manual soldering

The manual soldering should not be applied to the products, otherwise the housing may be deformed and/or the Au plating may be peeled off by heat.

#### Other notes

The use of infrared lamp causes the temperature at the resin to rise particularly too high.

All the temperatures in the product must be within the above diagram. Do not immerse the resin part into the solder. Even if within the above temperature diagram, there is a possibility that the gold wire in the products is broken in case that the deformation of PC board gives stress to the products.

Please confirm the conditions (including material and method of flux and cleaning) of the reflow soldering fully by actual solder reflow machine prior to the mass production use.

#### Treatment after open

- Reflow soldering must be done within 48 hours stored at the conditions of humidity 60% RH or less and temperature 10 to 30°C.
- 2. If the product must be stored after it is unpacked, store it in a dry box or reseal it in a moisture-proof package with desiccant at a temperature of 10 to 30°C and a humidity of 60% RH or less. Even then, mount the product within one week.

Please check each region's Terms & Conditions by region website.

#### OMRON Corporation Device & Module Solutions Company

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